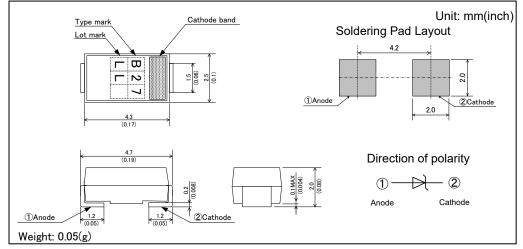


FEATURES

- High transient reverse power capability suitable
- Available for automotive use
- AEC-Q101 qualified
- RoHS compliant
- Molding compound equivalent to UL 94 V-0
- MSL equivalent to level 1
- Type of packaging: 1500pcs/tape and reel

OUTLINE DRAWING



ABSOLUTE MAXIMUM RATINGS

Items	Symbols	Units	Ratings
Non-Repetitive Peak Reverse One- Cycle Dissipation	0	14/	400 (10/1000µs waveform,Tj=25℃ start)
	P _{RSM}	W	600(Rectangular pulse t=0.1ms T _j =25°C start)
Surge(Non-Repetitive) Forward Current	I _{FSM}	А	40 (8.3ms single half sine-wave, T _i =40°C start)
Operating Junction Temperature	Tj	°C	-65 ~ +185
Storage Temperature	T _{stg}	°C	-65 ~ +185
Stand-off Voltage	V _{RM}	V	Refer to characteristics column

CHARACTERISTICS Vz=12~51V(TL=25°C)

			Charac	Maximum	Maximum		
Туре	Stand-off Voltage V _{RM} (V)	Zener Volt Minimum	age Vz (V) Maximum	Test Current Iz (mA)	Maximum Reverse Leakage at V _{RM} I _{RRM} (µA)	Peak Pulse Surge Current I _{PPM} (A)	Clamping Voltage at I _{PPM} V _C (V)
DAM1MB12	9.7	11.4	12.7	1	5	23.1	17.3
DAM1MB13	10.5	12.4	14.1	1	5	21.1	19.0
DAM1MB15	12.1	13.5	15.6	1	1	18.2	22.0
DAM1MB16	12.9	15.3	17.1	1	1	17.0	23.5
DAM1MB18	14.5	16.8	19.1	1	1	15.1	26.5
DAM1MB20	16.2	18.8	21.2	1	1	13.7	29.1
DAM1MB22	17.8	20.8	23.3	1	1	12.5	31.9
DAM1MB24	19.4	22.7	25.6	1	1	11.5	34.7
DAM1MB27	21.8	25.1	28.9	1	1	10.2	39.1
DAM1MB30	24.3	28.0	32.0	1	1	9.2	43.5
DAM1MB33	26.8	31.0	35.0	1	1	8.4	47.7
DAM1MB36	29.1	33.4	38.6	1	1	7.7	52.0
DAM1MB39	31.6	36.1	41.9	1	1	7.1	56.4
DAM1MB43	34.8	39.8	46.2	1	1	6.5	61.9
DAM1MB47	38.0	43.3	50.7	1	1	5.9	67.7
DAM1MB51	41.3	46.9	55.1	1	1	5.4	74.0

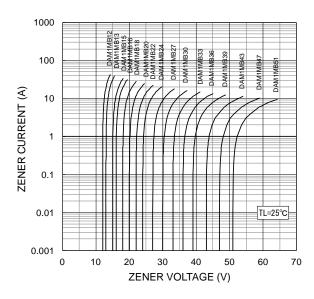


DAM1MB

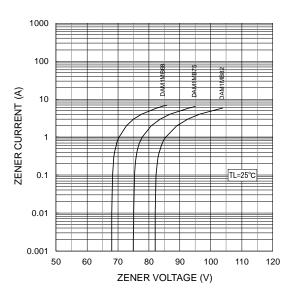
CHARACTERISTICS VZ=68~82V(TL=25°C)												
Туре	Stand-off	Zener Volt		teristics	Maximum	Maximum Peak	Maximum					
	Voltage V _{RM} (V)	Minimum	Maximum	Test Current Iz (mA)	Reverse Leakage at V _{RM} I _{RRM} (µA)	Peak Pulse Surge Current IPPм (A)	Clamping Voltage at I _{PPM} Vc (V)					
DAM1MB68	55.1	61.2	74.8	1	1	4.1	98.0					
DAM1MB75	60.7	67.5	82.5	1	1	3.7	107.6					
DAM1MB82	66.4	73.8	90.2	1	1	3.4	117.9					

Typical zener characteristics (Vz : 12 - 51V)

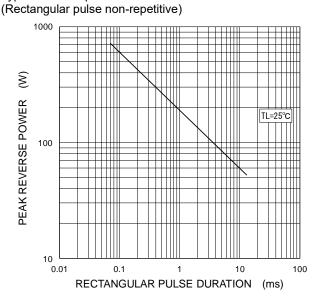
Typical reverse power characteristics



Typical zener characteristics (Vz : 68 - 82V)



Transient thermal impedance



Rth(j-a) TRANSIENT THERMAL IMPEDANCE (°C/W) 100 Rth(j-L) 10 1 0.1 0.1 TIME (s) 0.001 0.01 10 100

HITACHI

DAM1MB

Part number description

L B 2 7					B	2) (2 - 5) (3) 7 6)							
$ \begin{array}{ c c c c c c } \hline 1 & Type mark & "B" & : DAl \\ \hline 2 & Zener voltage & Zener voltage \\ \hline 3 & Zener voltage & e.g. 27 \rightarrow 2 \\ \hline 4 & Year & Year of ma \\ \hline 5 & Month & Month of m \\ \hline 6 & Blank & Here is blan \\ \hline \end{array} $	ige (tw 27V nufact ianufa	vo digi ure (t	ts) :he la	st dig	(it)									
Mark	A	В	С	D	Е	К	L	М	Ν	Х	Y	Z		
④ Year of manufacture (the last digit)	1	2	3	4	5	6	7	8	9	0	-	_		
⑤ Month of manufacture	1	2	3	4	5	6	7	8	9	10	11	12		
e.g. B27 Type: DAM"B LL Zener voltag Manufacturir	e: 27	V	ul. 2(017										

Precautions for Safe Use and Notices

If semiconductor devices are handled inappropriate manner, failures may result. For this reason, be sure to read "Precaution for Use" before use.

This mark indicates an item about which caution is required.

CAUTION

This mark indicates a potentially hazardous situation which, if not avoided, may result in minor or moderate injury and damage to property.

- (1) Regardless of changes in external conditions during use "absolute maximum ratings" should never be exceed in designing electronic circuits that employ semiconductors. In the case of pulse use, furthermore, "safe operating area(SOA)" precautions should be observed.
- (2) Semiconductor devices may experience failures due to accident or unexpected surge voltages. Accordingly, adopt safe design features, such as redundancy or prevention of erroneous action, to avoid extensive damage in the event of a failure.
- (3) In cases where extremely high reliability is required (such as use in nuclear power control, aerospace and aviation, traffic equipment, life-support-related medical equipment, fuel control equipment and various kinds of safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of user's fail-safe precautions or other arrangement. Or consult Hitachi's sales department staff.

(If a semiconductor device fails, there may be cases in which the semiconductor device, wiring or wiring pattern will emit smoke or cause a fire or in which the semiconductor device will burst)

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[Usage]

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